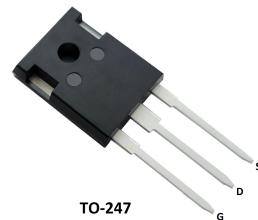


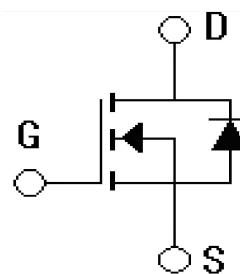
## Features

- $V_{DS}=1500V, I_D=12A$   
 $R_{DS(on)}<1.8\Omega @ V_{GS}=10V$
- High density cell design for ultra low  $R_{dson}$
- Low gate charge
- Improved dv/dt capability
- RoHS product



## Applications

- High Voltage Switched-mode and resonant-mode power supplies
- High Voltage Pulse Power Applications
- High Voltage Discharge circuits in Lasers Pulsers, Spark Igniters, RF Generators
- High Voltage DC-DC converters
- High Voltage DC-AC inverters



## Absolute Ratings ( $T_c=25^\circ C$ )

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DSS}$	1500	V
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Drain Current-continuous	$I_D, 25^\circ C$	12	A
	$100^\circ C$	8	
Drain Current-pulse(note1)*	$I_{DM}$	22	A
Single Pulsed Avalanche Energy (note2)	$E_{AS}$	607	mJ
Maximum Power Dissipation	PD $TC=25^\circ C$ Derate above $25^\circ C$	860	W
		6.8	W/ $^\circ C$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	$^\circ C$
Maximum lead Storage Temperature Range Purposes	TL	300	$^\circ C$

\*Drain current limited by maximum junction temperature

**Electrical Characteristics**( $T_{CASE}=25^{\circ}\text{C}$  unless otherwise specified)

Parameter	Symbol	Tests conditions	Min	Typ	Max	Units
Drain-Source Voltage	$\text{BV}_{\text{DSS}}$	$I_{\text{D}}=1\text{mA}, V_{\text{GS}}=0\text{V}$	1500	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=V_{\text{DSS}}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 30\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA

**On-Characteristics**

Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2.0	-	5.5	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=1\text{A}$	-	1.3	1.8	$\Omega$
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=20\text{V}, I_{\text{D}}=6\text{A}$ (note3)	-	17	-	S

**Dynamic Characteristics**

Input capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHZ}$	-	4874	-	pF
Output capacitance	$C_{\text{oss}}$		-	310	-	pF
Reverse transfer capacitance	$C_{\text{rss}}$		-	20	-	pF
Total Gate Charge	$Q_{\text{g}}$	$V_{\text{DS}}=750\text{V}, I_{\text{D}}=6\text{A}, V_{\text{GS}}=10\text{V}$ (note3,4)		97		nC
Gate-Source Charge	$Q_{\text{gs}}$			34		nC
Gate-Drain Charge	$Q_{\text{gd}}$			35		nC

**Electrical Characteristics**( $T_{CASE}=25^{\circ}\text{C}$  unless otherwise specified)

Parameter	Symbol	Tests conditions	Min	Typ	Max	Units
Parameter	Symbol	Tests conditions	Min	Typ	Max	Units
Turn-On delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DS}}=750\text{V}, I_{\text{D}}=6\text{A}, V_{\text{GS}}=10\text{V}$ (note3,4)	-	118	-	ns
Turn-On rise time	$t_{\text{r}}$		-	73	-	ns
Turn-Off delay time	$t_{\text{d}(\text{off})}$		-	260	-	ns
Turn-Off rise time	$t_{\text{f}}$		-	64	-	ns

Maximum Continuous Drain-Source Diode Forward Current	$V_{SD}$	$V_{GS}=0V, I_S=12A$	0.5	-	1.2	V
Diode Forward Current	$I_S$	$TC=25^\circ C$	-	-	12	A
Reverse recovery time	$T_{rr}$	$I_S=6A, dI/dT=100A/\mu S$ $VR=100V, VGS=0V$ (note4)	-	0.37	-	$\mu S$
Reverse Recovery Charge				3.28		$\mu C$

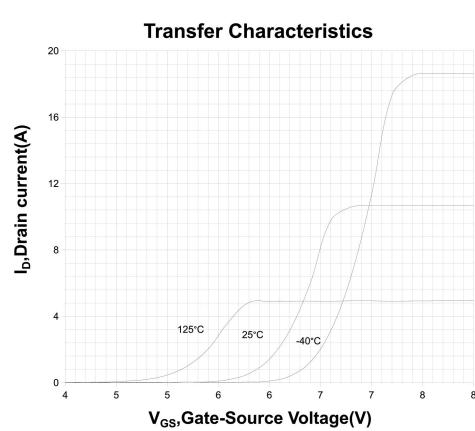
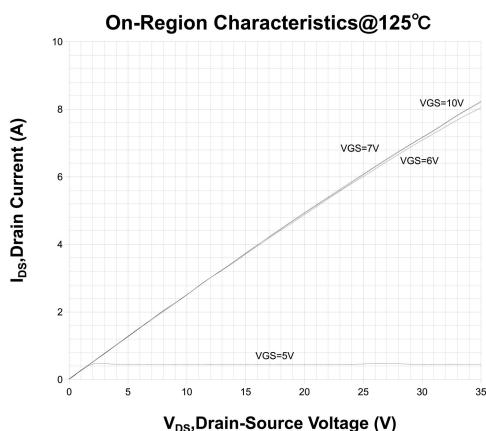
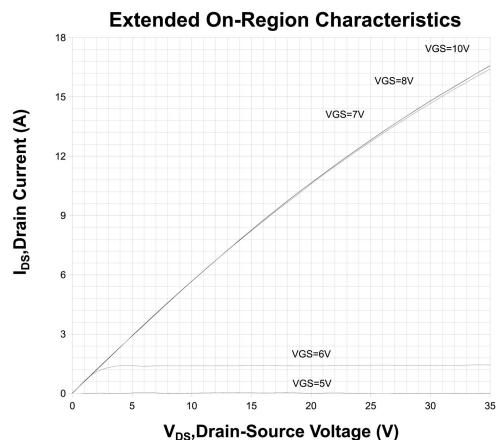
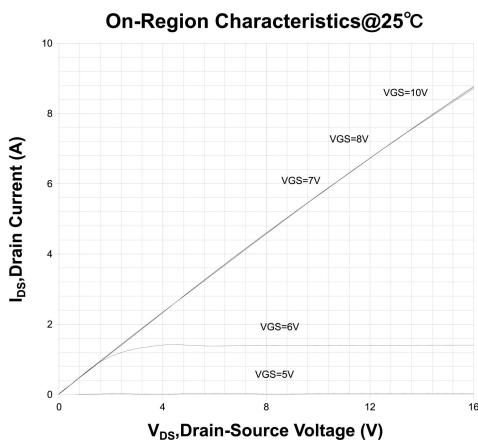
## Thermal Characteristic

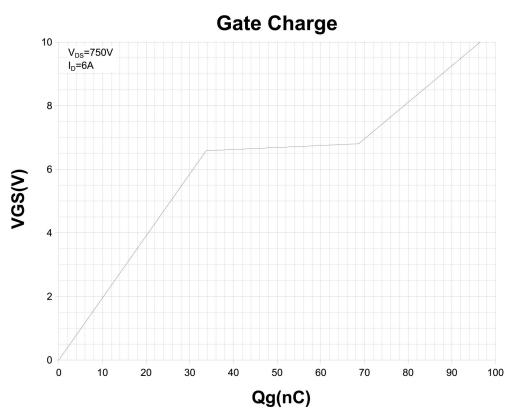
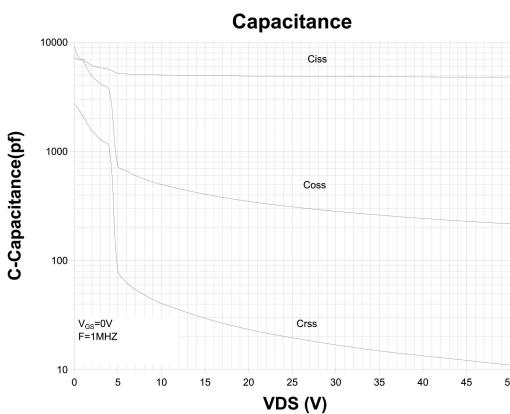
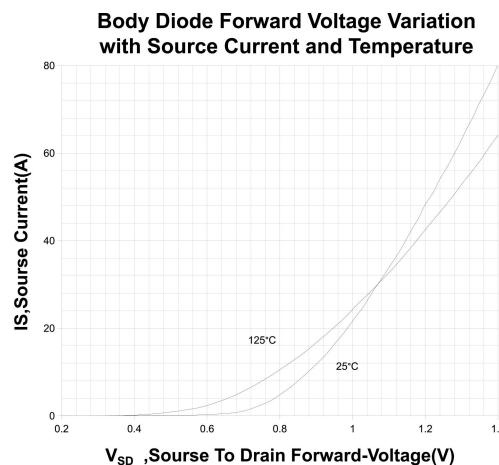
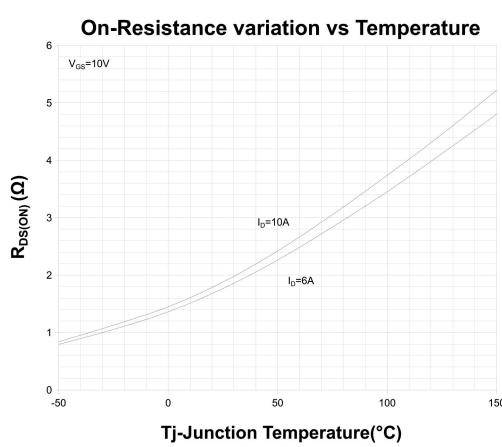
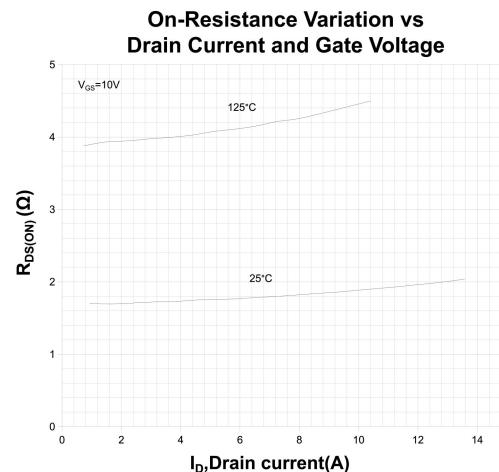
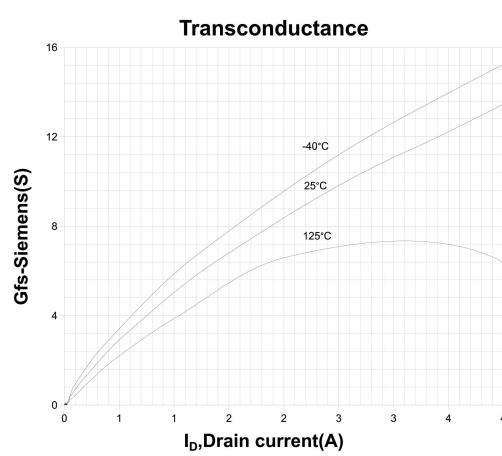
Parameter	Symbol	Value	Unit
Thermal Resistance,junction to Case	$R_{th}(j-C)$	0.18	$^\circ C/W$
Thermal Resistance,junction to ambient	$R_{th}(j-A)$	36	$^\circ C/W$

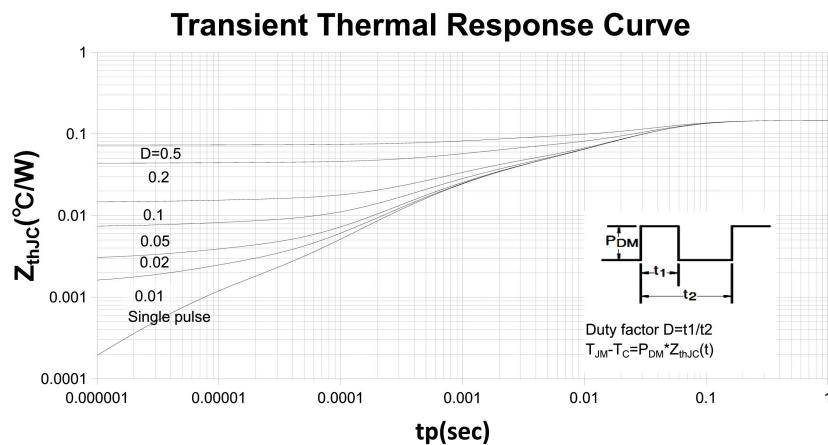
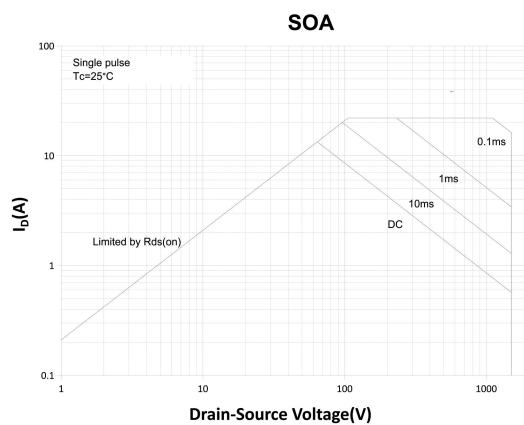
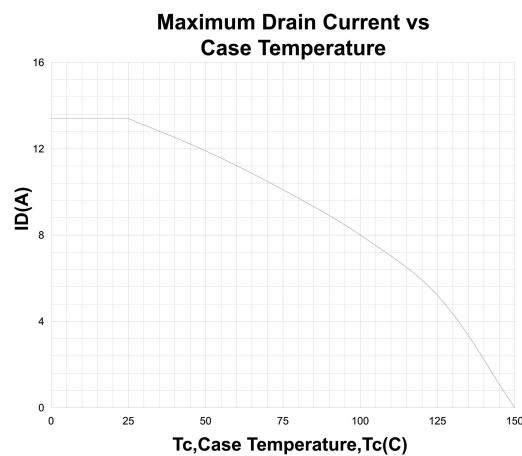
Notes:

- Repetitive Rating : Pulse width limited by maximum junction temperature
- $L = 15 \text{ mH}$ ,  $I_{AS} = 9 \text{ A}$ ,  $V_{DD} = 50 \text{ V}$ ,  $R_G = 25 \Omega$ , Starting  $T_J = 25^\circ C$
- Pulse Test : Pulse width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$
- Essentially independent of operating temperature

## Electrical Characteristics







## Package Mechanical DATA

